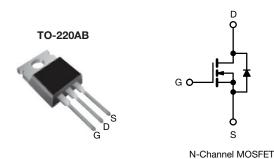
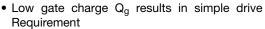
Vishay Siliconix

Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	500			
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	0.28		
Q _g max. (nC)	130			
Q _{gs} (nC)	33			
Q _{gd} (nC)	59			
Configuration	Single			

FEATURES





• Improved gate, avalanche, and dynamic dV/dt ruggedness

RoHS*

- Fully characterized capacitance and avalanche voltage and current
- · Low t_{rr} and soft diode recovery
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- · High speed power switching
- · ZVS and high frequency circuit
- PWM inverters

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRFB17N50LPbF

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unle	ess otherwis	e noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	500	V	
Gate-source voltage			V_{GS}	± 30	v	
Continuous drain current	V _{GS} at 10 V	T _C = 25 °C		16		
		T _C = 100 °C	I _D	11	Α	
Pulsed drain current ^a			I _{DM}	64		
Linear derating factor				1.8	W/°C	
Single pulse avalanche energy ^b			E _{AS}	390	mJ	
Repetitive avalanche current ^a			I _{AR}	16	А	
Repetitive avalanche energy ^a			E _{AR}	22	mJ	
Maximum power dissipation	$T_C = 1$	25 °C	P _D	220	W	
Peak diode recovery dV/dt ^c			dV/dt	13	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d	For 10 s			300	7	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Starting T_J = 25 °C, L = 3.0 mH, R_g = 25 Ω , I_{AS} = 16 A (see fig. 12)
- c. $I_{SD} \le 16$ A, $dI/dt \le 347$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	0.56		

PARAMETER	SYMBOL	TES	ST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static					•			
Drain-source breakdown voltage	V _{DS}	V _{GS}	500	-	-	V		
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.6	-	V/°C	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} :	= V _{GS} , I _D = 250 μA	3.0	-	5.0	V	
Gate-source leakage	I _{GSS}		V _{GS} = ± 30 V		_	± 100	nA	
Zava gata valtaga dvain avvvant		$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$		-	-	50	μΑ	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 400 \text{V}$	$V, V_{GS} = 0 V, T_{J} = 125 ^{\circ}C$	-	-	2.0	mA	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 9.9 A ^b	-	0.28	0.32	Ω	
Forward transconductance	9 _{fs}	V _{DS} = 50 V, I _D = 9.9 A ^b		11	-	-	S	
Dynamic								
Input capacitance	C_{iss}		-	2760	-			
Output capacitance	C _{oss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ f = 1.0 MHz, see fig. 5		-	325		-	
Reverse transfer capacitance	C_{rss}			-	37		-	
Output consoitance		$V_{GS} = 0 V$	V _{DS} = 1.0 V , f = 1.0 MHz	-	3690	-	- pF	
Output capacitance	C_{oss}	V _{GS} = 0 V	V _{GS} = 0 V V _{DS} = 400 V , f = 1.0 MHz		84	-	1	
Effective output capacitance	C _{oss} eff.	V _{GS} = 0 V	V _{DS} = 0 V to 400 V ^c	-	159	-		
Total gate charge	Qg			-	-	130		
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_{D} = 16 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 b		-	33	nC	
Gate-drain charge	Q_{gd}	see lig. 0 and 10		-	-	59		
Turn-on delay time	t _{d(on)}	V_{DD} = 250 V, I_{D} = 16 A, R_{g} = 7.5 Ω , see fig. 10 b		-	21	-	- ns	
Rise time	t _r			-	51	-		
Turn-off delay time	t _{d(off)}			-	50	-		
Fall time	t _f			-	28	-		
Gate input resistance	R _g	f = 1 MHz, open drain		0.3	-	1.4	Ω	
Drain-Source Body Diode Characteristic	cs							
Continuous source-drain diode current	I _S	MOSFET sym	bol	-	-	16		
Pulsed diode forward current ^a	I _{SM}	showing the integral reverse p - n junction diode		-	-	64	А	
Body diode voltage	V_{SD}	T _J = 25 °C, I _S = 16 A, V _{GS} = 0 V ^b		-	-	1.5	V	
Body diode reverse recovery time	t _{rr}	T _J = 25 °C		-	170	250	- ns	
		T _J = 125 °C	$T_J = 25 ^{\circ}\text{C}$ $I_F = 16 \text{A, dl/dt} = 100 \text{A/} \mu \text{s}^{ \text{D}}$		220	330		
Body diode reverse recovery charge	Q _{rr}	T _J = 25 °C			470	710	nC	
		T _J = 125 °C			810	1210		
Reverse recovery current	I _{RRM}		•	-	7.3	11	Α	
Forward turn-on time	t _{on}	Intrinsic tu	ırn-on time is negligible (turn-	on is don	ninated b	y L _S and	L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

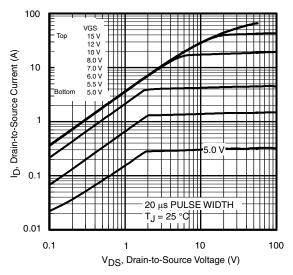


Fig. 1 - Typical Output Characteristics

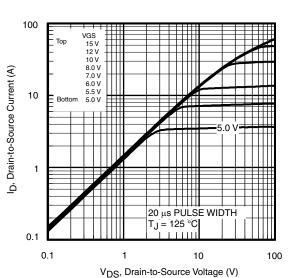


Fig. 2 - Typical Output Characteristics

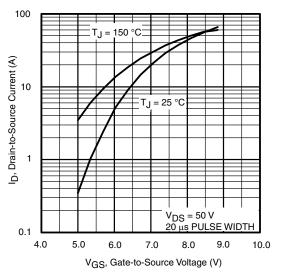


Fig. 3 - Typical Transfer Characteristics

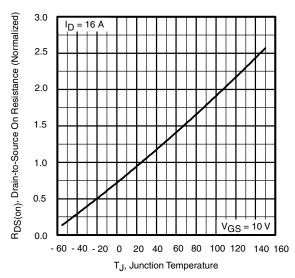


Fig. 4 - Normalized On-Resistance vs. Temperature



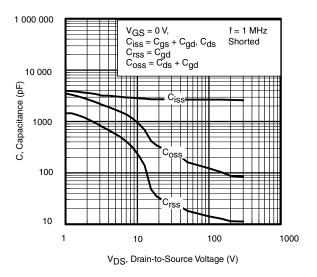


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

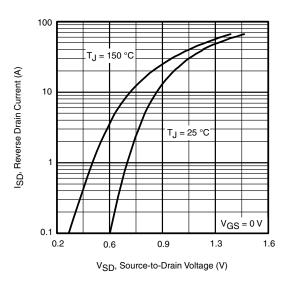


Fig. 7 - Typical Source-Drain Diode Forward Voltage

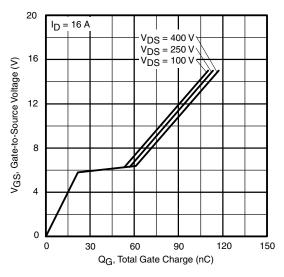


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

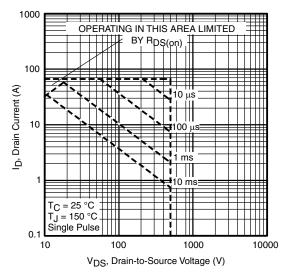


Fig. 8 - Maximum Safe Operating Area



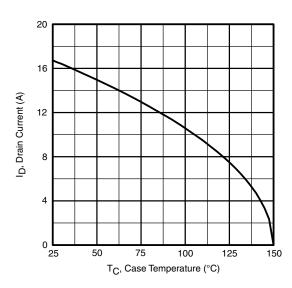


Fig. 9 - Maximum Drain Current vs. Case Temperature

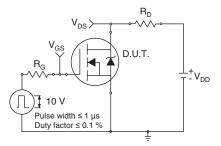


Fig. 10a - Switching Time Test Circuit

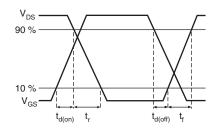


Fig. 10b - Switching Time Waveforms

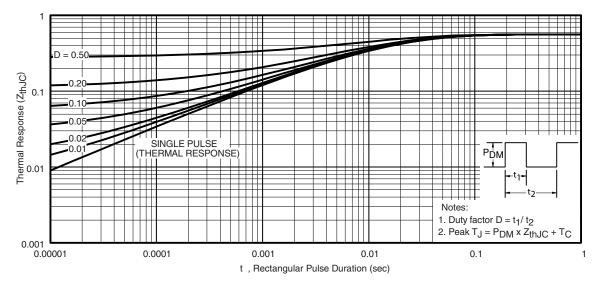


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

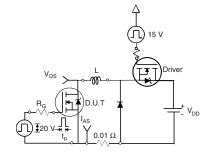


Fig. 12a - Unclamped Inductive Test Circuit

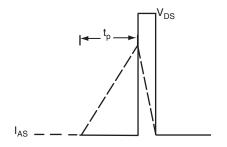


Fig. 12b - Unclamped Inductive Waveforms



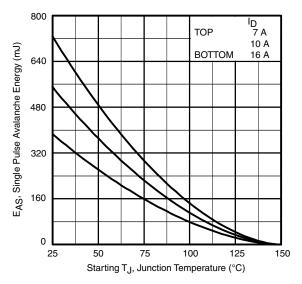


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

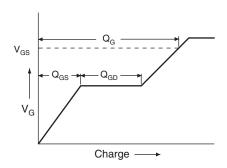


Fig. 13a - Basic Gate Charge Waveform

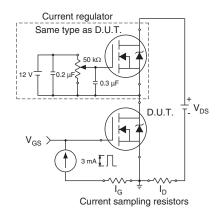
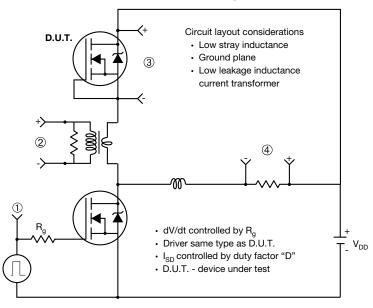


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



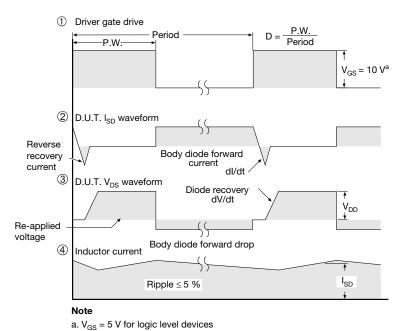


Fig. 14 - For N-Channel

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